

Microelectronics International

Number 2

- 2 Access this journal online
- 3 Modelling and wave velocity calculation of multilayer structure SAW sensors
Dejan V. Tošić and Marija F. Hribšek
- 8 Overview and outlook of through-silicon via (TSV) and 3D integrations
John H. Lau
- 23 Testing on dynamic behavior of PBGA assembly by considering fixed-modes
Ping Yang and Zixia Chen
- 30 DC magnetron sputter-deposited tungsten silicide films for microelectronic applications
Jian-Wei Hoon, Kah-Yoong Chan and Teck-Yong Tou
- 34 Stabilization network optimization of internally matched GaN HEMTs
W.J. Luo, X.J. Chen, C.Y. Yang, Y.K. Zheng, K. Wei and X.Y. Liu
- 38 A low-power CMOS DC-DC buck converter with on-chip stacked spiral inductor
Chan-Soo Lee, Ho-Yong Choi, Yeong-Seuk Kim and Nam-Soo Kim
- 44 X-ray diffraction studies of $\text{Al}_x\text{Ga}_{1-x}\text{N}$ ($0 \leq x \leq 1$) ternary alloys grown on sapphire substrate
Ng Sha Shiong, Ching Chin Guan, Zainuriah Hassan and Haslan Abu Hassan
- 49 An investigation into the effect of fabrication parameter variation on the characteristics of screen-printed thick-film silver/silver chloride reference electrodes
J.K. Atkinson, M. Glanc, P. Boltryk, M. Sophocleous and E. Garcia-Breijo
- 53 Response of Ag thick film microstrip straight resonator to perturbation of bulk and thick film $\text{Ni}_{1-x}\text{Cu}_x\text{Mn}_2\text{O}_4$ ($0 \leq x \leq 1$) ceramics
R.N. Jadhav and Vijaya Puri
- 58 Industry news
- 62 New products
- 67 Appointments
- 69 Conferences and exhibitions
- 73 International diary

